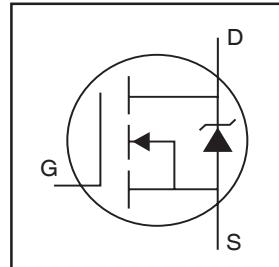


International **IR** Rectifier

PD - 95156

IRLZ44NS/LPbF

HEXFET® Power MOSFET

	$V_{DSS} = 55V$ $R_{DS(on)} = 0.022\Omega$ $I_D = 47A$
--	--

- Logic-Level Gate Drive
- Advanced Process Technology
- Surface Mount (IRLZ44NS)
- Low-profile through-hole (IRLZ44NL)
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Lead-Free

Description

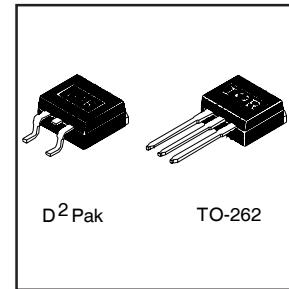
Fifth Generation HEXFETs from International Rectifier utilize advanced processing techniques to achieve extremely low on-resistance per silicon area. This benefit, combined with the fast switching speed and ruggedized device design that HEXFET Power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in a wide variety of applications.

The D²Pak is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D²Pak is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0W in a typical surface mount application.

The through-hole version (IRLZ44NL) is available for low-profile applications.

Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ ⑤	47	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$ ⑤	33	
I_{DM}	Pulsed Drain Current ①⑤	160	
$P_D @ T_A = 25^\circ C$	Power Dissipation	3.8	W
$P_D @ T_C = 25^\circ C$	Power Dissipation	110	W
	Linear Derating Factor	0.71	W/°C
V_{GS}	Gate-to-Source Voltage	±16	V
E_{AS}	Single Pulse Avalanche Energy②⑤	210	mJ
I_{AR}	Avalanche Current①	25	A
E_{AR}	Repetitive Avalanche Energy①	11	mJ
dv/dt	Peak Diode Recovery dv/dt ③⑤	5.0	V/ns
T_J	Operating Junction and	-55 to + 175	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	



Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{θJC}$	Junction-to-Case	---	1.4	°C/W
$R_{θJA}$	Junction-to-Ambient (PCB Mounted,steady-state)**	---	40	

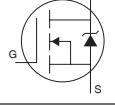
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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{DSS}}$	Drain-to-Source Breakdown Voltage	55	—	—	V	$V_{GS} = 0V, I_D = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{DSS}}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.070	—	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}, I_D = 1\text{mA}$ ⑤
$R_{DS(\text{on})}$	Static Drain-to-Source On-Resistance	—	—	0.022	Ω	$V_{GS} = 10V, I_D = 25\text{A}$ ④
		—	—	0.025		$V_{GS} = 5.0V, I_D = 25\text{A}$ ④
		—	—	0.035		$V_{GS} = 4.0V, I_D = 21\text{A}$ ④
$V_{GS(\text{th})}$	Gate Threshold Voltage	1.0	—	2.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
g_f	Forward Transconductance	21	—	—	S	$V_{DS} = 25V, I_D = 25\text{A}$ ⑤
I_{DSS}	Drain-to-Source Leakage Current	—	—	25	μA	$V_{DS} = 55V, V_{GS} = 0V$
		—	—	250		$V_{DS} = 44V, V_{GS} = 0V, T_J = 150^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 16V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -16V$
Q_g	Total Gate Charge	—	—	48	nC	$I_D = 25\text{A}$
Q_{gs}	Gate-to-Source Charge	—	—	8.6		$V_{DS} = 44V$
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	—	25		$V_{GS} = 5.0V, \text{See Fig. 6 and 13}$ ④⑤
$t_{d(on)}$	Turn-On Delay Time	—	—	11	ns	$V_{DD} = 28V$
t_r	Rise Time	—	—	84		$I_D = 25\text{A}$
$t_{d(off)}$	Turn-Off Delay Time	—	—	26		$R_G = 3.4\Omega, V_{GS} = 5.0V$
t_f	Fall Time	—	—	15		$R_D = 1.1\Omega, \text{See Fig. 10}$ ④⑤
L_S	Internal Source Inductance	—	7.5	—	nH	Between lead, and center of die contact
C_{iss}	Input Capacitance	—	1700	—	pF	$V_{GS} = 0V$
C_{oss}	Output Capacitance	—	400	—		$V_{DS} = 25V$
C_{rss}	Reverse Transfer Capacitance	—	150	—		$f = 1.0\text{MHz}, \text{See Fig. 5}$ ⑤

Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	47	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ①	—	—	160		
V_{SD}	Diode Forward Voltage	—	—	1.3	V	$T_J = 25^\circ\text{C}, I_S = 25\text{A}, V_{GS} = 0V$ ④
t_{rr}	Reverse Recovery Time	—	80	120	ns	$T_J = 25^\circ\text{C}, I_F = 25\text{A}$
Q_{rr}	Reverse Recovery Charge	—	210	320	nC	$dI/dt = 100\text{A}/\mu\text{s}$ ④⑤
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L_S+L_D)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

③ $I_{SD} \leq 25\text{A}$, $di/dt \leq 270\text{A}/\mu\text{s}$, $V_{DD} \leq V_{(\text{BR})\text{DSS}}$, $T_J \leq 175^\circ\text{C}$

② $V_{DD} = 25V$, starting $T_J = 25^\circ\text{C}$, $L = 470\mu\text{H}$
 $R_G = 25\Omega$, $I_{AS} = 25\text{A}$. (See Figure 12)

④ Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.

⑤ Uses IRLZ44N data and test conditions

** When mounted on 1" square PCB (FR-4 or G-10 Material).

For recommended footprint and soldering techniques refer to application note #AN-994.

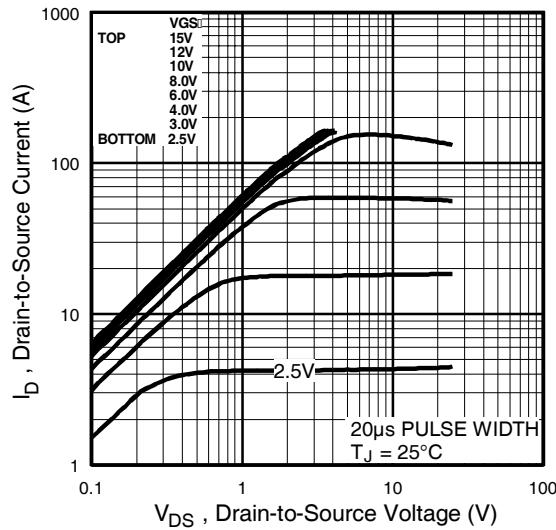


Fig 1. Typical Output Characteristics

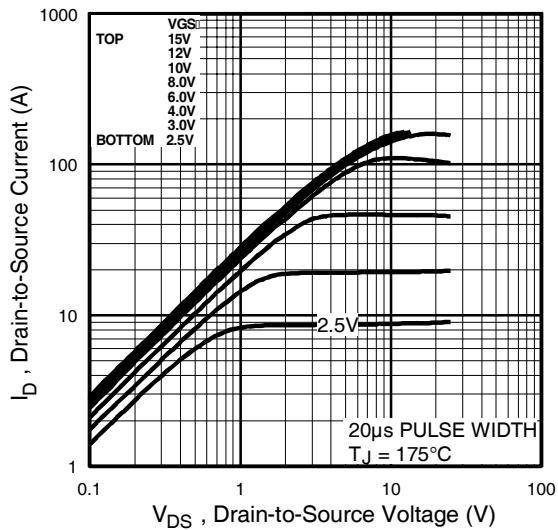


Fig 2. Typical Output Characteristics

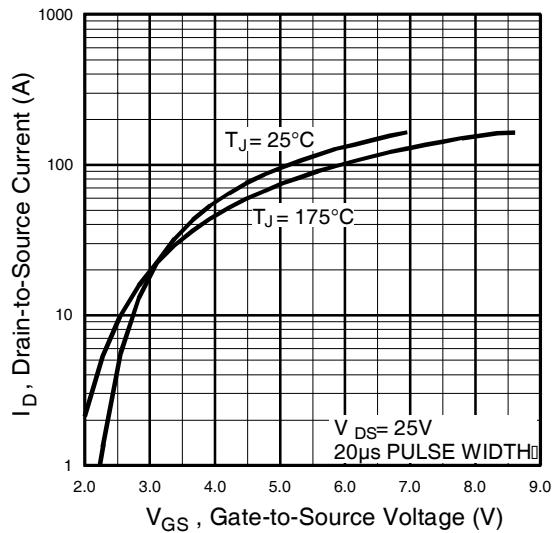


Fig 3. Typical Transfer Characteristics

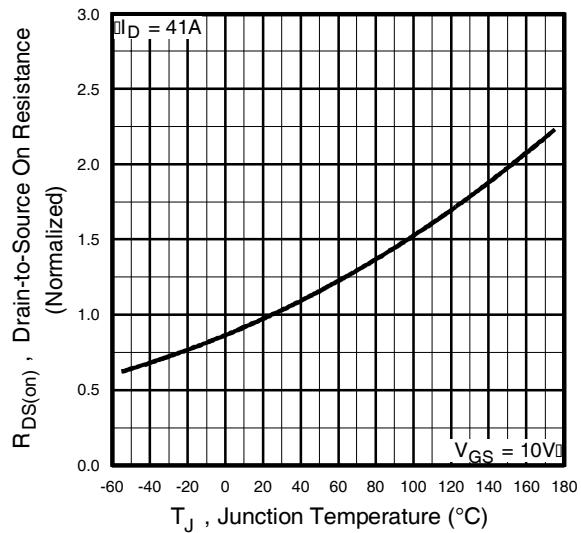


Fig 4. Normalized On-Resistance
Vs. Temperature

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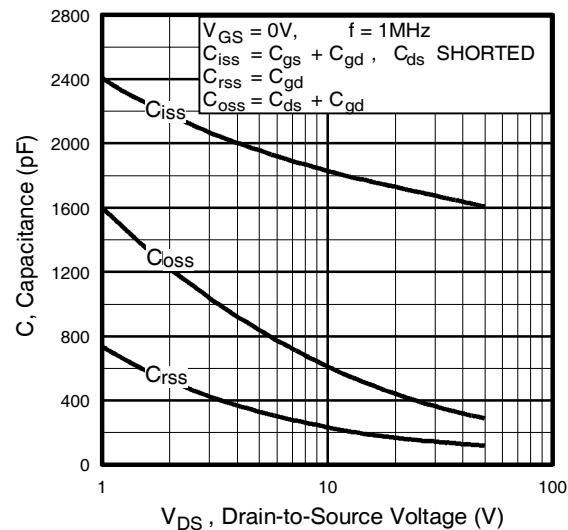


Fig 5. Typical Capacitance Vs.
Drain-to-Source Voltage

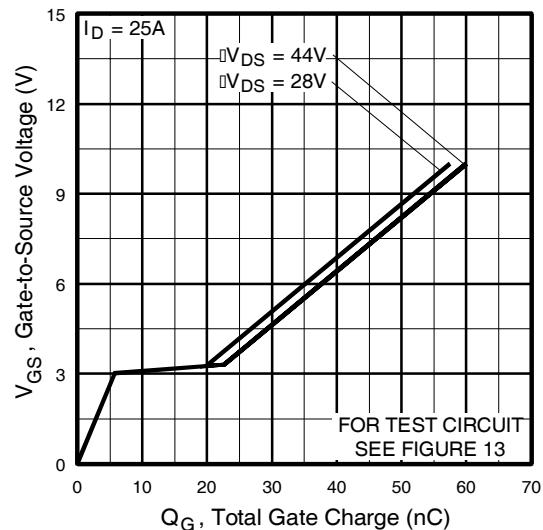


Fig 6. Typical Gate Charge Vs.
Gate-to-Source Voltage

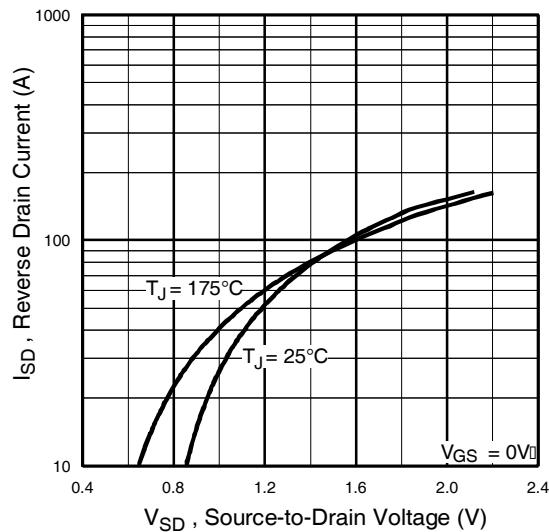


Fig 7. Typical Source-Drain Diode
Forward Voltage

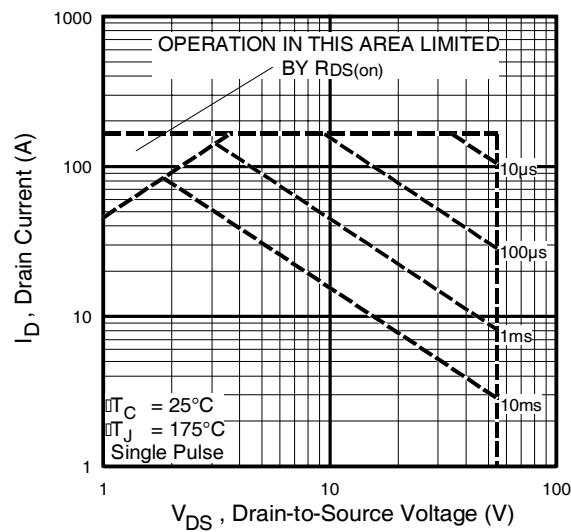


Fig 8. Maximum Safe Operating Area

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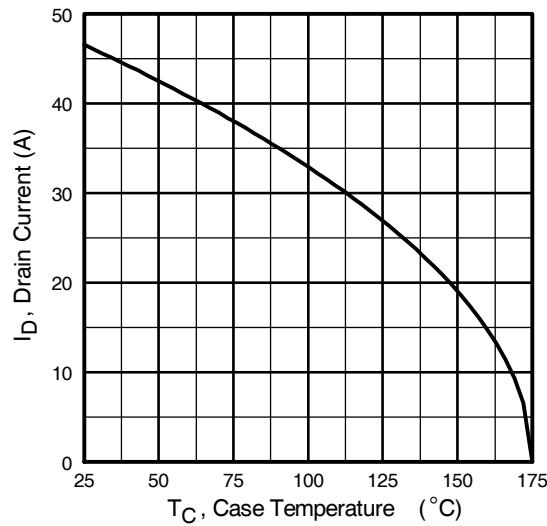


Fig 9. Maximum Drain Current Vs.
Case Temperature

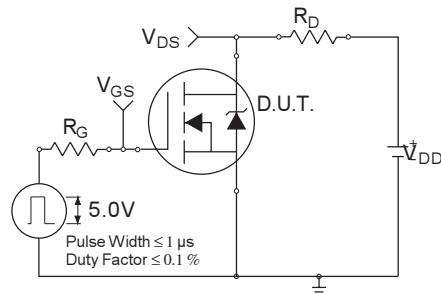


Fig 10a. Switching Time Test Circuit

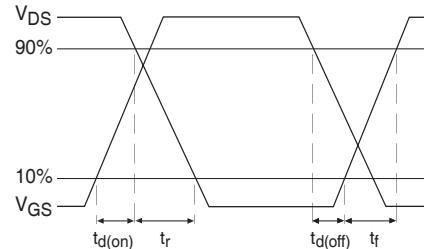


Fig 10b. Switching Time Waveforms

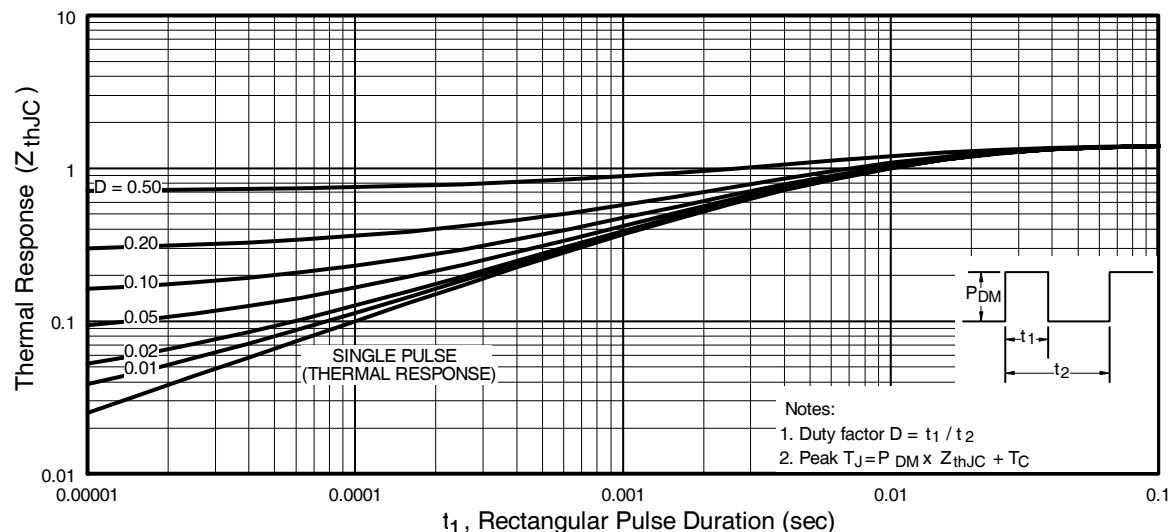


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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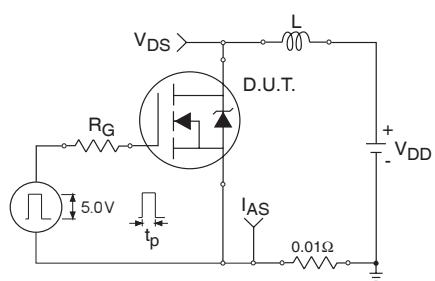


Fig 12a. Unclamped Inductive Test Circuit

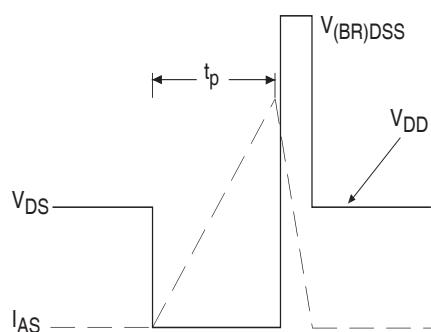


Fig 12b. Unclamped Inductive Waveforms

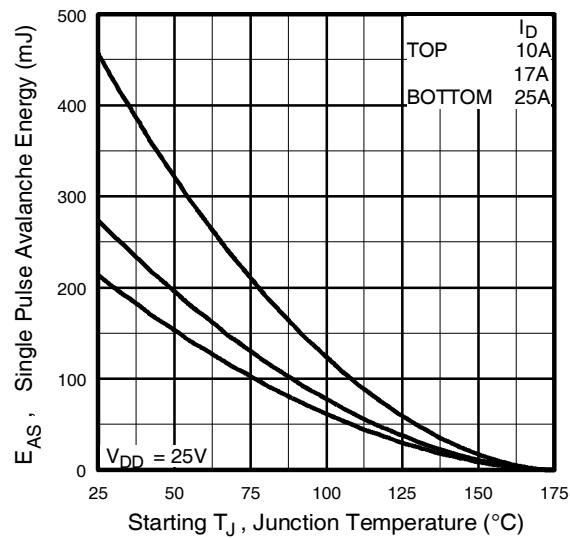


Fig 12c. Maximum Avalanche Energy
Vs. Drain Current

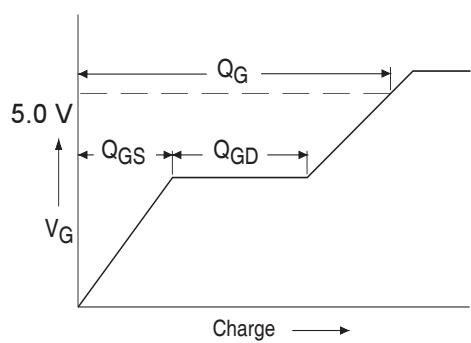


Fig 13a. Basic Gate Charge Waveform

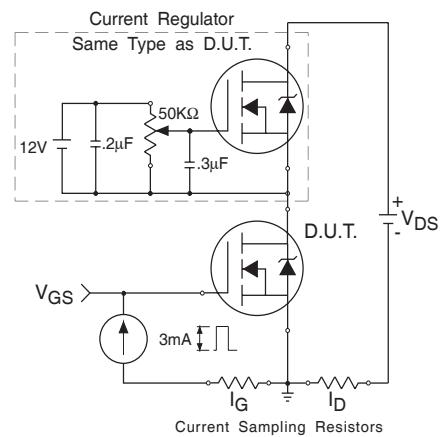


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit

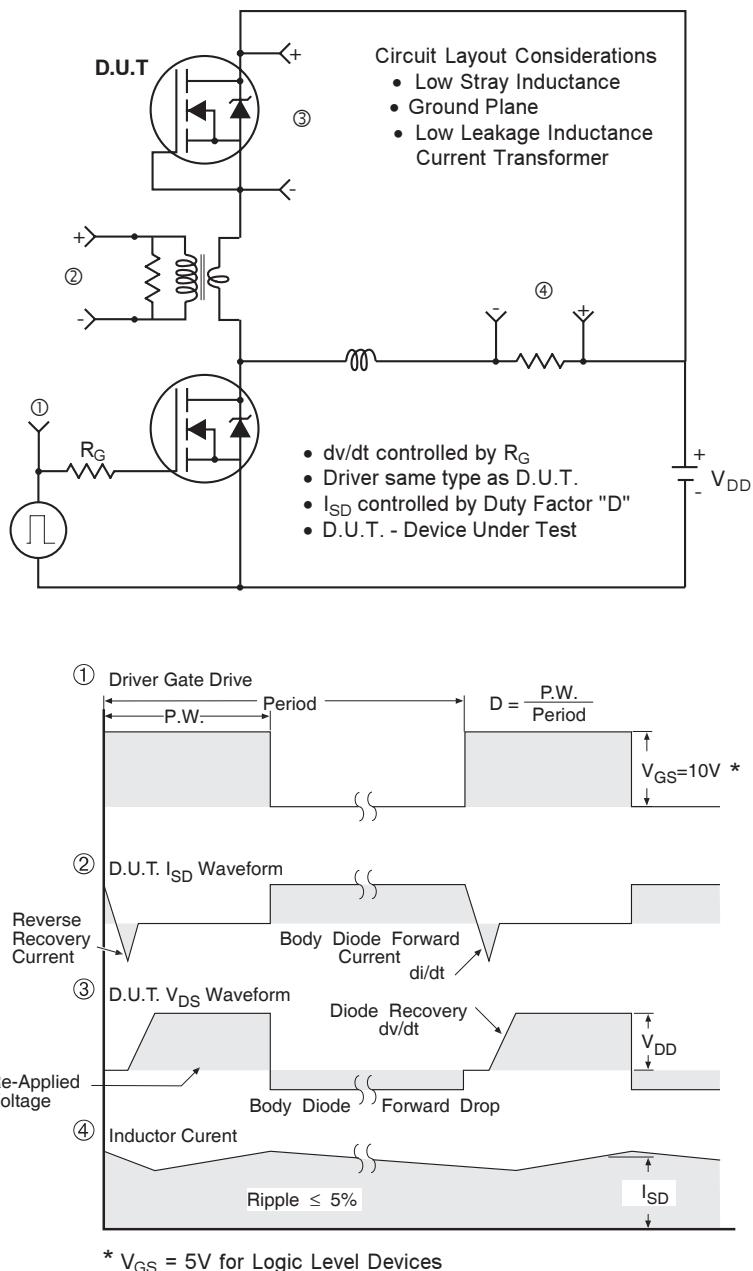


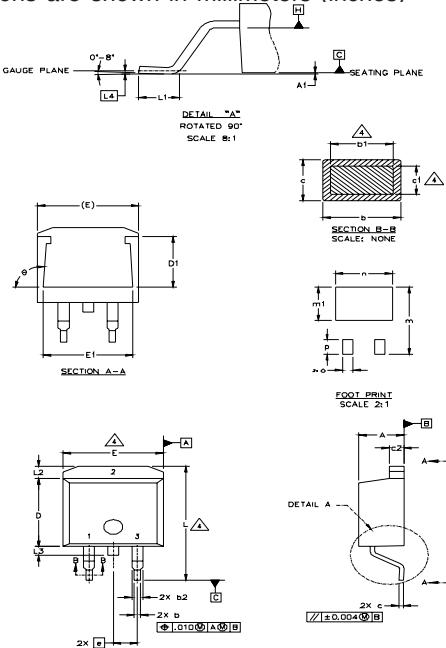
Fig 14. For N-Channel HEXFETs

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D²Pak Package Outline

Dimensions are shown in millimeters (inches)



SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	4.06	4.83	.160	.190	
A1		0.127		.005	
b	0.51	0.99	.020	.039	
b1	0.51	0.89	.020	.035	4
b2	1.14	1.40	.045	.055	
c	0.43	0.63	.017	.025	
c1	0.38	0.74	.015	.029	4
c2	1.14	1.40	.045	.055	
D	8.51	9.65	.335	.380	3
D1	5.33		.210		
E	9.65	10.67	.380	.420	3
E1	6.22		.245		
e	2.54	BSC	.100	BSC	
L	14.61	15.88	.575	.625	
L1	1.78	2.79	.070	.110	
L2		1.65		.065	
L3	1.27	1.78	.050	.070	
L4		0.25	BSC	.010	BSC
m	17.78		.700		
m1	8.89		.350		
n	11.43		.450		
o	2.08		.082		
p	3.81		.150		
θ	90°	93°	90°	93°	

LEAD ASSIGNMENTS

HEXFET	IGBTs...CoPACK	DIODES
1.— GATE	1.— GATE	1.— ANODE *
2.— DRAIN	2.— COLLECTOR	2.— CATHODE
3.— SOURCE	3.— Emitter	3.— ANODE

* PART DEPENDENT.

NOTES:

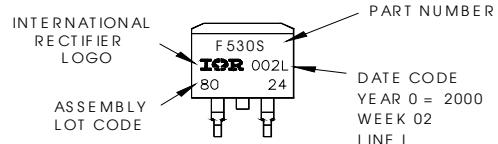
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES]
3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
4. DIMENSION b1 AND c1 APPLY TO BASE METAL ONLY.
5. CONTROLLING DIMENSION: INCH.



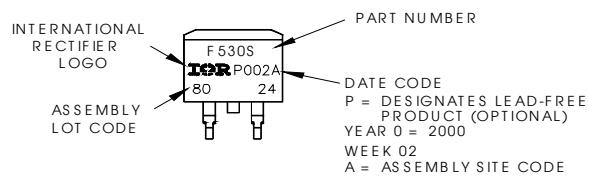
D²Pak Part Marking Information (Lead-Free)

EXAMPLE: THIS IS AN IRF530S WITH
LOT CODE 8024
ASSEMBLED ON WO 02, 2000
IN THE ASSEMBLY LINE "L"

Note: "P" in assembly line position indicates "Lead-Free"



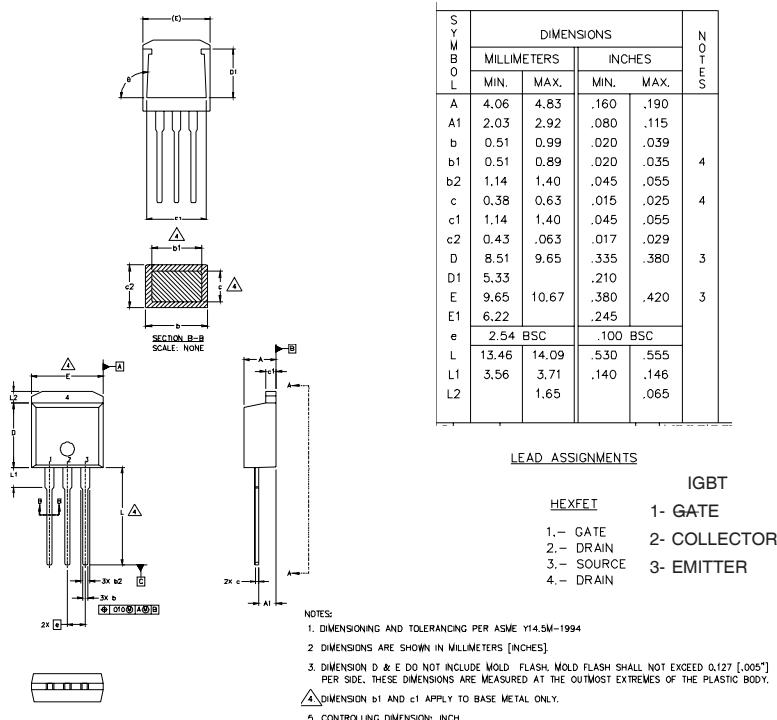
OR



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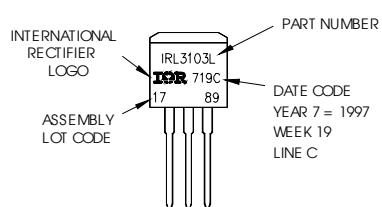
TO-262 Package Outline



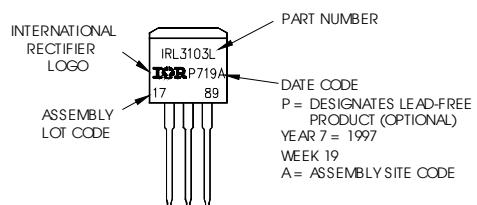
TO-262 Part Marking Information

EXAMPLE: THIS IS AN IRL3103L
 LOT CODE 1789
 ASSEMBLED ON WW 19, 1997
 IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line
 position indicates "Lead-Free"

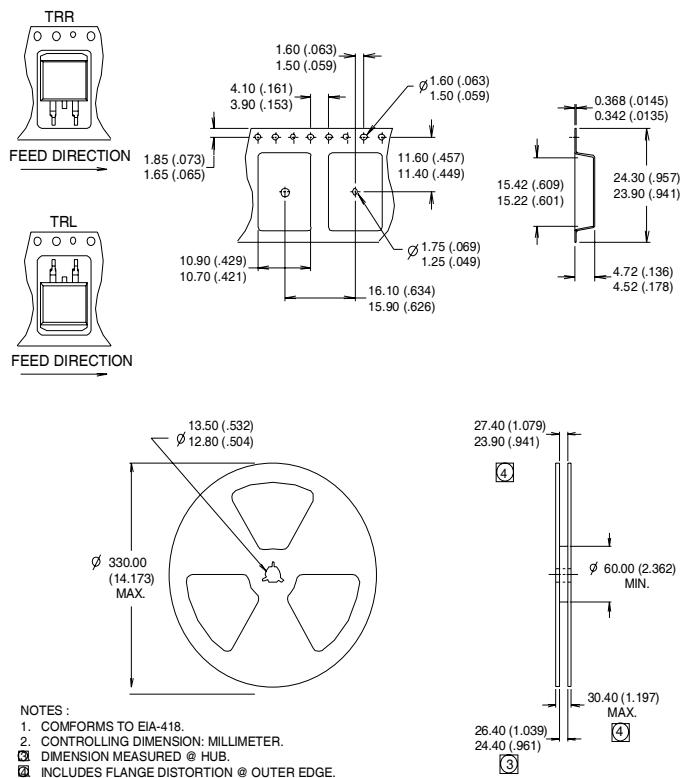


OR



D²Pak Tape & Reel Infomation

Dimensions are shown in millimeters (inches)



Data and specifications subject to change without notice.

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IR Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
 TAC Fax: (310) 252-7903
 Visit us at www.irf.com for sales contact information.04/04

Note: For the most current drawings please refer to the IR website at:
<http://www.irf.com/package/>

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